

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

APPLICANT:	C. Huang	CONF. NO.:	7288
U.S. SERIAL NO:	10/696,198	EXAMINER:	H. Trinh
FILED:	October 28, 2003	GROUP:	2814
FOR:	MULTI-CHIP PACKAGE DEVICE WITH HEAT SINK AND FABRICATION METHOD THEREOF		

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir/Madam:

**RESPONSE TO OFFICE ACTION**

Applicant is in receipt of the Office Action dated October 26, 2007 of the above-referenced application. Applicant responds to the Office Action as follows.

Claims 1-8 are pending in the application.

Claims 1-4 and 6-8 were rejected under 35 USC 103(a) as being unpatentable over U.S. Patent Application Publication US 2004/0099945 to Ku (hereinafter "Ku"). Claim 5 was rejected under 35 USC 103(a) as being unpatentable over Ku in view of U.S. Patent Application Publication US 2003/0089977 to Chee et al. These rejections are respectfully traversed.

The Ku reference does not teach or suggest a multi-chip package device in which a heat sink includes at least one hollow part adjusted in size depending on the thickness of the heat sink to effectively release thermal stresses from the heat sink, as recited in independent claim 1.

On page 3 of the Office Action of 10/26/2007, an aperture 504 of a thermal bridge 50 was cited as allegedly corresponding to the Applicant's claimed "at least one hollow part."